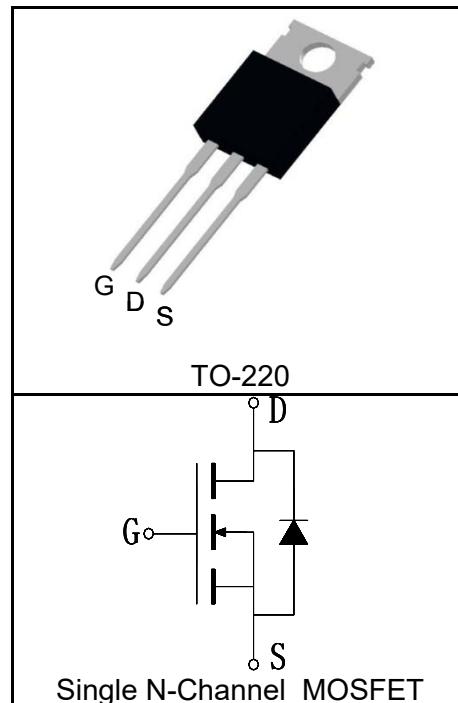


## Features

- 100V/130A,
- $R_{DS\ (ON)} = 6.7\text{m}\Omega$ (Typ.)@ $V_{GS}=10\text{V}$
- Low  $R_{DS\ (ON)}$
- Super High Dense Cell Design
- Reliable and Rugged
- 100% Avalanche Tested

## Pin Description



## Applications

- DC-DC Converters and Off-line UPS
- Power Management in Inverter System



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
<b>Common Ratings</b> ( $T_C=25^\circ\text{C}$ Unless Otherwise Noted)			
$V_{DSS}$	Drain-Source Voltage	100	V
$V_{GSS}$	Gate-Source Voltage	$\pm 25$	
$T_J$	Maximum Junction Temperature	175	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 175	$^\circ\text{C}$
$I_S$	Diode Continuous Forward Current	$T_C=25^\circ\text{C}$	130
<b>Mounted on Large Heat Sink</b>			
$I_{DP}^{(1)}$	300 $\mu\text{s}$ Pulse Drain Current Tested	$T_C=25^\circ\text{C}$	520
$I_D^{(2)}$	Continuous Drain Current( $V_{GS}=10\text{V}$ )	$T_C=25^\circ\text{C}$	130
		$T_C=100^\circ\text{C}$	92
$P_D$	Maximum Power Dissipation	$T_C=25^\circ\text{C}$	230
		$T_C=100^\circ\text{C}$	115
$R_{\theta JC}$	Thermal Resistance-Junction to Case	0.65	$^\circ\text{C/W}$
$R_{\theta JA}^{(3)}$	Thermal Resistance-Junction to Ambient	62.5	$^\circ\text{C/W}$
<b>Drain-Source Avalanche Ratings</b>			
$E_{AS}^{(4)}$	Avalanche Energy, Single Pulsed	900	mJ

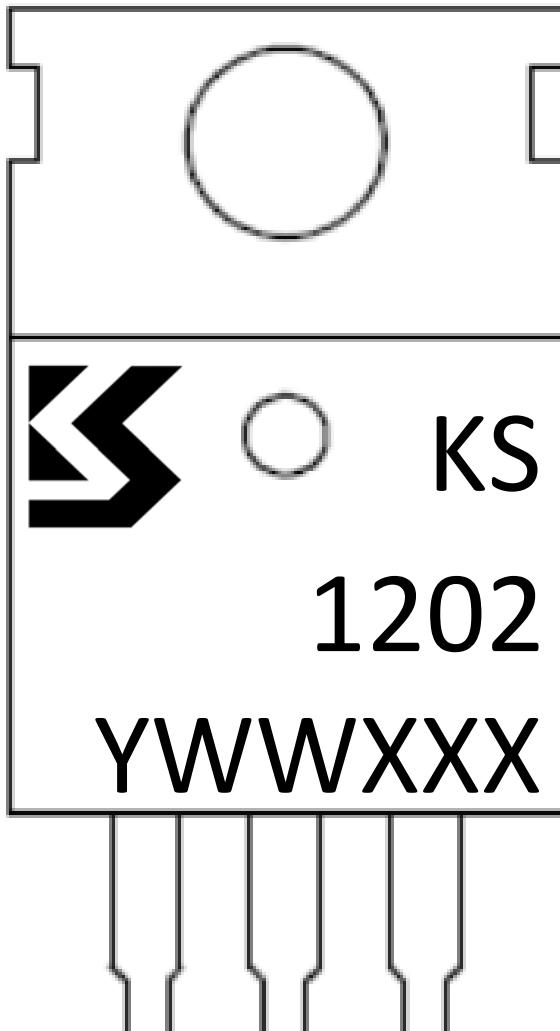
**Electrical Characteristics (T<sub>C</sub>=25°C Unless Otherwise Noted)**

Symbol	Parameter	Test Condition	KS1202CC			Unit
			Min.	Typ.	Max.	
<b>Static Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>DS</sub> =250μA	100			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V			1	μA
		T <sub>J</sub> =125°C			30	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250μA	2		4	V
I <sub>GSS</sub>	Gate Leakage Current	V <sub>GS</sub> =±25V, V <sub>DS</sub> =0V			±100	nA
R <sub>DS(ON)</sub> <sup>⑤</sup>	Drain-Source On-state Resistance	V <sub>GS</sub> =10V, I <sub>DS</sub> =40A		6.7	8	mΩ
<b>Diode Characteristics</b>						
V <sub>SD</sub> <sup>⑤</sup>	Diode Forward Voltage	I <sub>SD</sub> =40A, V <sub>GS</sub> =0V		0.84	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>SD</sub> =40A, dI <sub>SD</sub> /dt=100A/μs		28		ns
Q <sub>rr</sub>	Reverse Recovery Charge			110		nC
<b>Dynamic Characteristics<sup>⑥</sup></b>						
R <sub>G</sub>	Gate Resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz		3.2		Ω
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =50V, Frequency=1.0MHz		4090		pF
C <sub>oss</sub>	Output Capacitance			470		
C <sub>rss</sub>	Reverse Transfer Capacitance			310		
t <sub>d(ON)</sub>	Turn-on Delay Time	V <sub>DD</sub> =50V, I <sub>DS</sub> =40A, V <sub>GEN</sub> =10V, R <sub>G</sub> =3Ω		28		ns
t <sub>r</sub>	Turn-on Rise Time			60		
t <sub>d(OFF)</sub>	Turn-off Delay Time			86		
t <sub>f</sub>	Turn-off Fall Time			23		
<b>Gate Charge Characteristics<sup>⑥</sup></b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =50V, V <sub>GS</sub> =10V, I <sub>DS</sub> =40A		69		nC
Q <sub>gs</sub>	Gate-Source Charge			23		
Q <sub>gd</sub>	Gate-Drain Charge			22		

- Notes:
- ①Pulse width limited by safe operating area.
  - ②Calculated continuous current based on maximum allowable junction temperature. The package limitation current is 75A.
  - ③When mounted on 1 inch square copper board, t≤10sec. The value in any given application depends on the user's specific board design.
  - ④Limited by T<sub>Jmax</sub>, I<sub>AS</sub> =60A, L=0.5mH, V<sub>DD</sub> = 48V, R<sub>G</sub> = 25Ω , Starting TJ = 25°C.
  - ⑤Pulse test; Pulse width≤300μs, duty cycle≤2%.
  - ⑥Guaranteed by design, not subject to production testing.

**Ordering and Marking Information**

Device	Package	Packaging	Quantity	Reel Size	Tape width
KS1202CC	TO-220	Tube	50	-	-

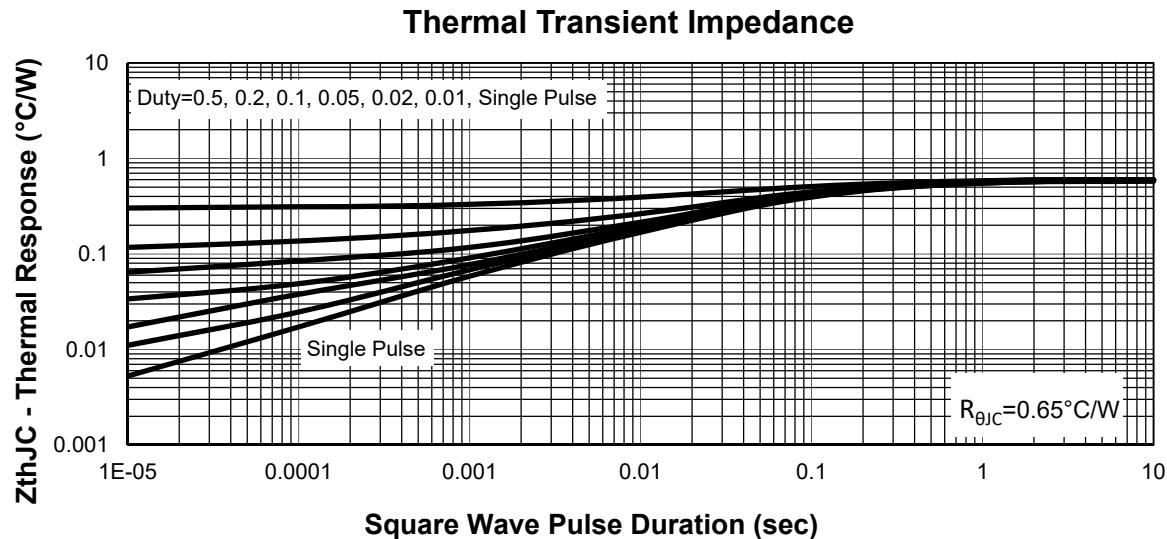
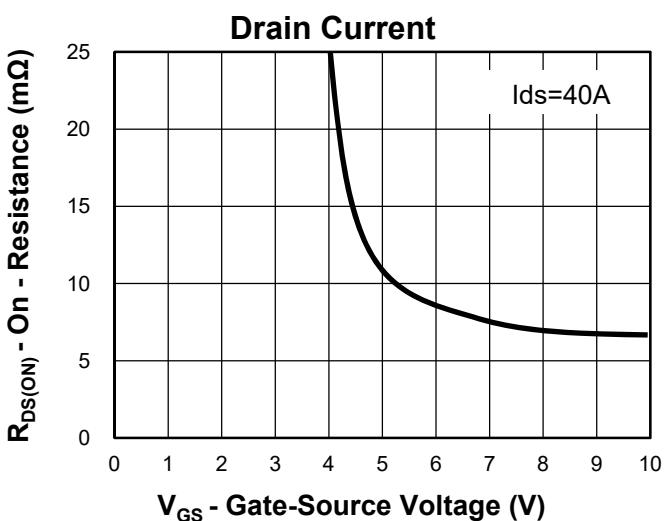
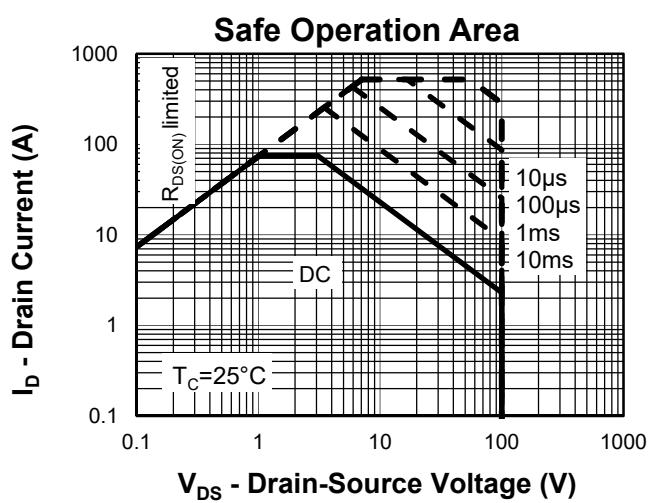
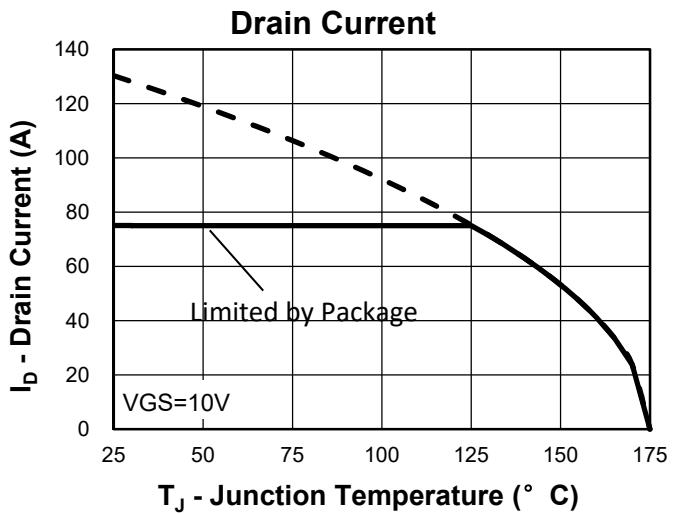
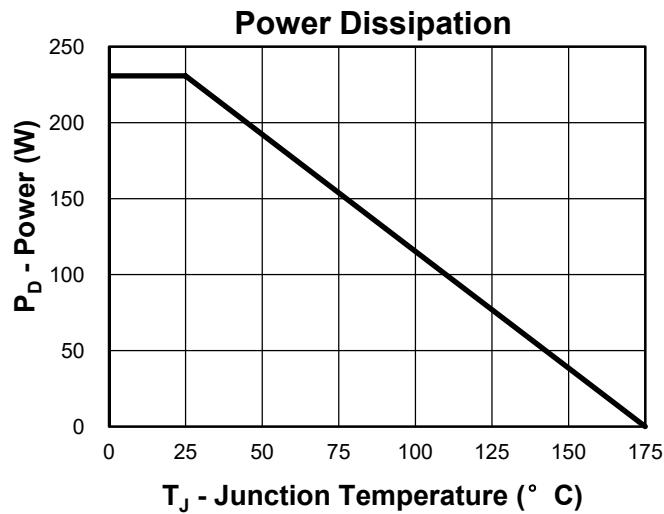


Y =Year, 2017-A, 2018-B,etc.

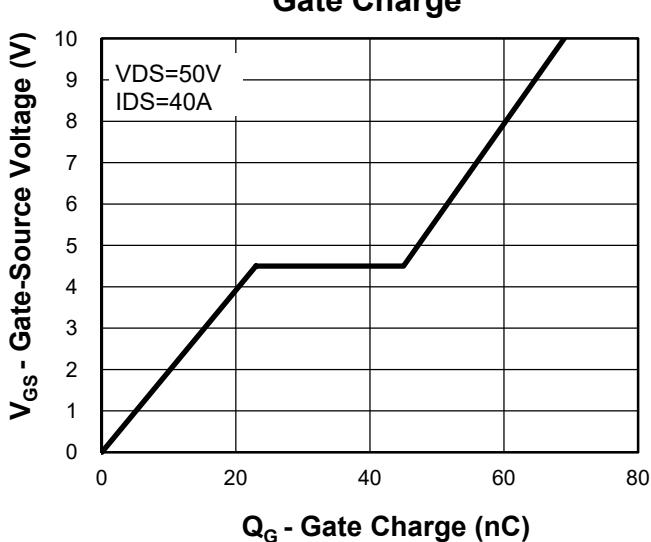
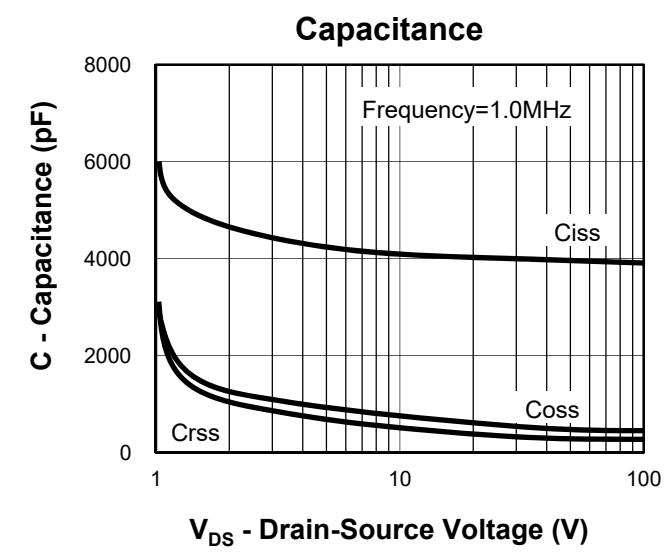
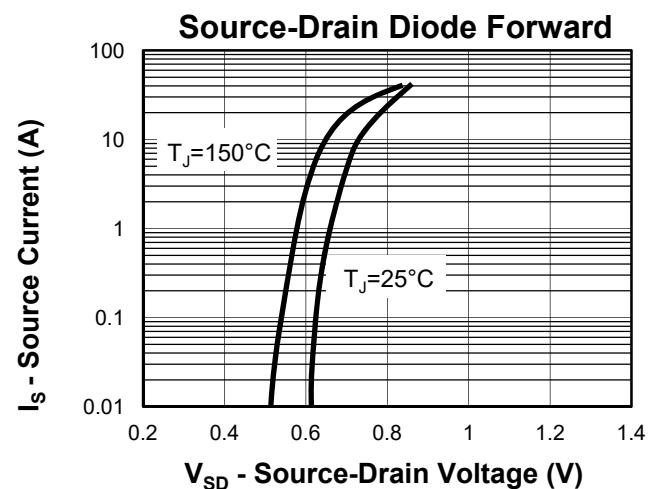
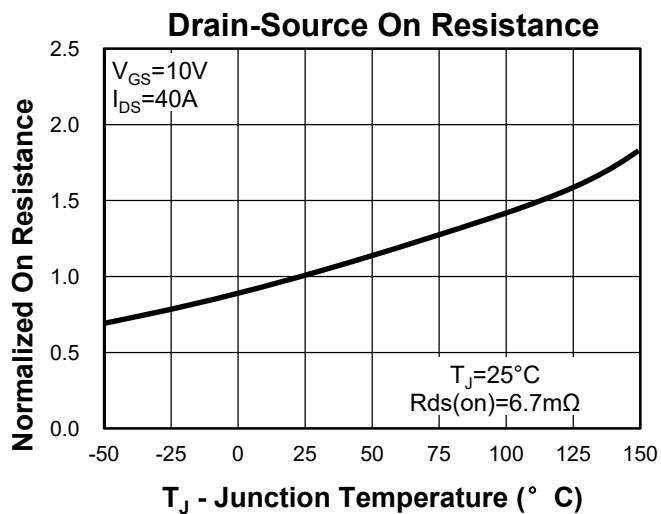
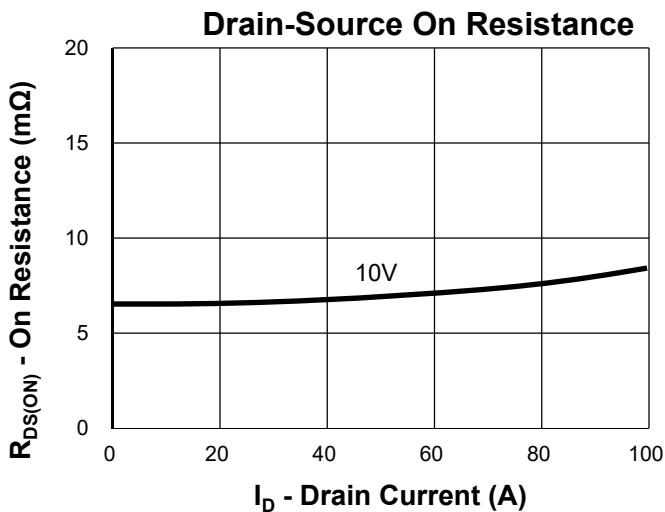
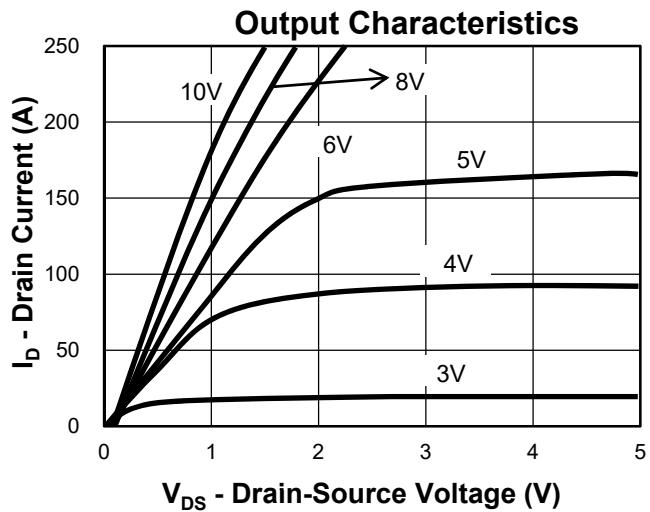
WW =Week.

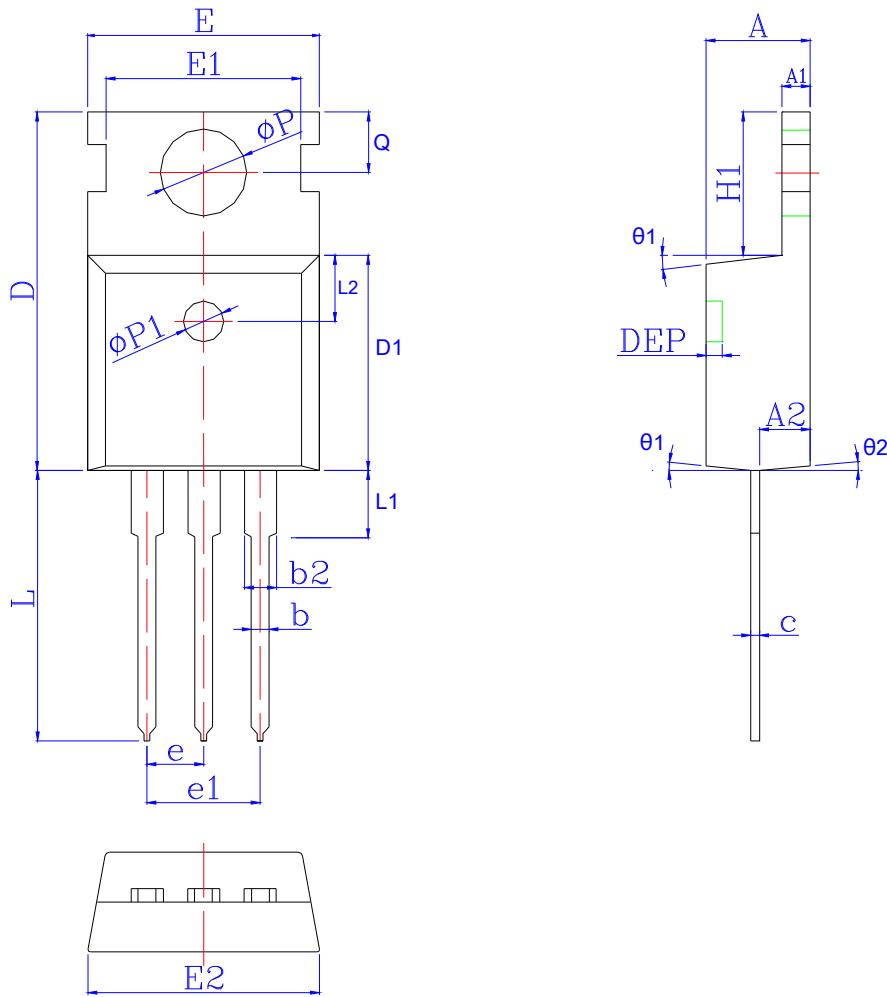
XXX =Lot number.

## Typical Characteristics



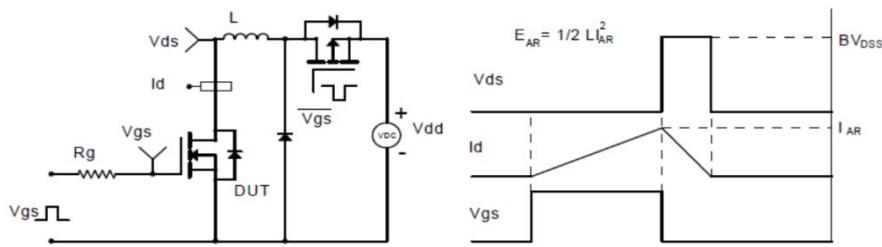
## Typical Characteristics



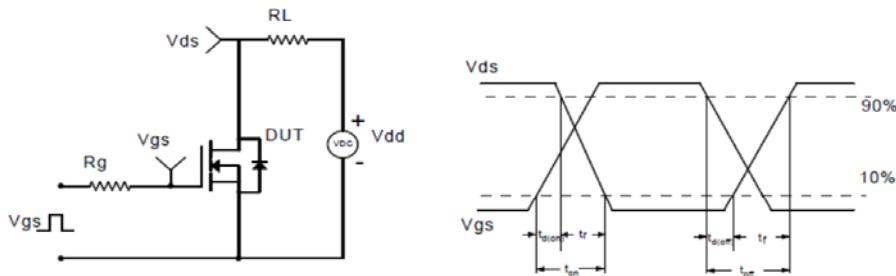
**Package Information**
**TO-220**


SYMBOL	MM			INCH			SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX		MIN	NOM	MAX	MIN	NOM	MAX
A	4.30	4.54	4.77	0.169	0.179	0.188	Φp1	1.40	1.50	1.60	0.055	0.059	0.063
A1	1.15	1.30	1.40	0.045	0.051	0.055	e	2.54 BSC			0.10 BSC		
A2	1.90	2.25	2.60	0.075	0.089	0.102	e1	5.08 BSC			0.20 BSC		
b	0.60	0.80	1.00	0.024	0.031	0.039	H1	6.30	6.50	6.80	0.248	0.256	0.268
b2	1.17	1.28	1.72	0.046	0.050	0.068	L	12.70	13.18	13.65	0.500	0.519	0.537
c	0.40	0.50	0.60	0.016	0.020	0.024	L1	*	*	3.95	*	*	0.156
D	15.40	15.70	16.00	0.606	0.618	0.630	L2	2.50 REF			0.098 REF		
D1	8.96	9.21	9.46	0.353	0.363	0.372	Φp	3.50	3.60	3.75	0.138	0.142	0.148
DEP	*	*	0.30	*	*	0.012	Q	2.70	2.80	3.20	0.106	0.110	0.126
E	9.66	9.97	10.28	0.380	0.393	0.405	θ1	5°	7°	9°	5°	7°	9°
E1	*	8.70	*	*	0.343	*	θ2	1°	3°	5°	1°	3°	5°
E2	9.80	10.00	10.20	0.386	0.394	0.402							

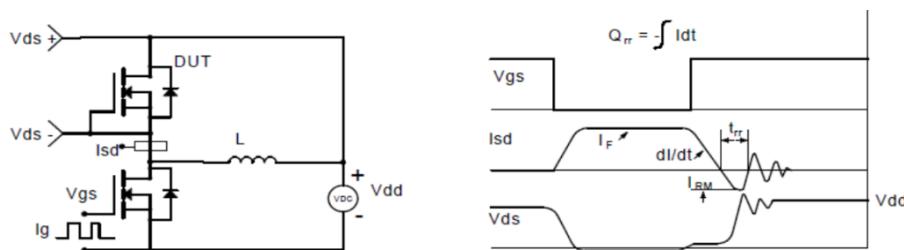
### Avalanche Test Circuit and Waveforms



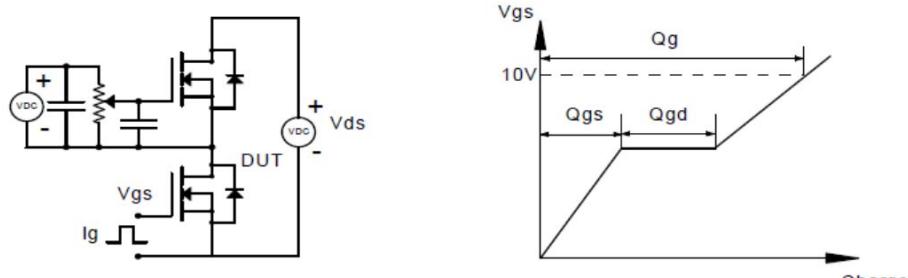
### Switching Time Test Circuit and Waveforms



### Diode Recovery Test Circuit and Waveforms



### Gate Charge Test Circuit and Waveform



### Customer Service

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